



### **N-Channel Super Junction Power MOSFET** II

#### **General Description**

The series of devices use advanced super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

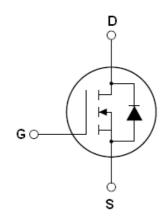
#### **Features**

- New technology for high voltage device
- ●Low on-resistance and low conduction losses
- ●Small package
- Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

V <sub>DS</sub> @T <sub>jmax</sub>	710	V
R <sub>DS(ON)</sub> TYP	2.2	Ω
$I_D$	1.8	A



Schematic diagram

#### **Package Marking And Ordering Information**

Device	Device Package	Marking
NCE65R2K4I	TO-251	NCE65R2K4I
NCE65R2K4K	TO-252	NCE65R2K4K





TO-251

**TO-252** 

Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V <sub>GS</sub> =0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V)	V <sub>GS</sub>	±30	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	1.8	Α
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	1.2	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	5.4	Α
Maximum Power Dissipation(Tc=25℃)	$P_{D}$	22	W
Derate above 25°C		0.176	w/°C
Single pulse avalanche energy (Note2)	Eas	40	mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	0.9	Α
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	E <sub>AR</sub>	0.06	mJ



## NCE65R2K4I, NCE65R2K4K

Parameter	Symbol	Value	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55+150	°C

#### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	5.68	°C W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	75	°C W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Table 3. Liectifical Characteristics	cs (1A-23 Cumess otherwise noted)					
Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			10	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.5	3	3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =1A		2200	2400	mΩ
Dynamic Characteristics			•	•		•
Forward Transconductance	<b>g</b> FS	$V_{DS} = 20V, I_{D} = 0.9A$		1.9		S
Input Capacitance	C <sub>iss</sub>	\/ -50\/\/ -0\/		183		PF
Output Capacitance	Coss	- V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,		12		PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz		1.0		PF
Total Gate Charge	Qg	\/ 400\/\ 40A		3.0	10	nC
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =480V,I <sub>D</sub> =1.8A,		0.6		nC
Gate-Drain Charge	$Q_{gd}$	- V <sub>GS</sub> =10V		1.1		nC
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		10		Ω
Switching times			•			
Turn-on Delay Time	t <sub>d(on)</sub>			6		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =380V, $I_{D}$ =0.9A,		3		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=50\Omega, V_{GS}=10V$		64		nS
Turn-Off Fall Time	t <sub>f</sub>			11		nS
Source- Drain Diode Characteristics		•	•	•		•
Source-drain current(Body Diode)	I <sub>SD</sub>	T 05°0			1.8	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	- T <sub>C</sub> =25°C			5.4	Α
Forward On Voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =1.8A,V <sub>GS</sub> =0V		1	1.3	V
Reverse Recovery Time	t <sub>rr</sub>			135		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> =1.8A,di/dt=100A/μs		0.6		uC
Peak reverse recovery current	I <sub>rrm</sub>			8.2		Α
reak reverse recovery current	ırrm			0.2		

Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> Tj=25°C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 





#### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

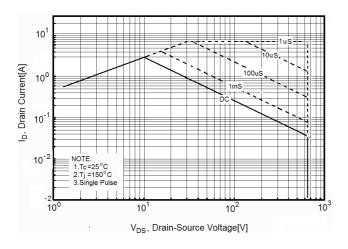


Figure 3. Output characteristics

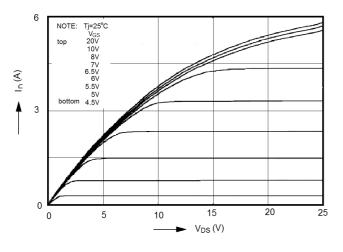


Figure 5. Static drain-source on resistance

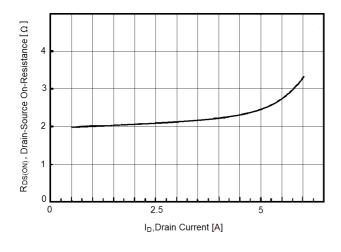


Figure 2. Source-Drain Diode Forward Voltage

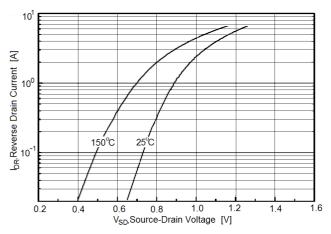


Figure 4. Transfer characteristics

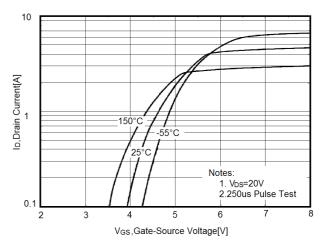


Figure 6. R<sub>DS(ON)</sub> vs Junction Temperature

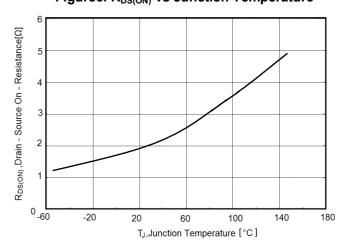






Figure 7. BV<sub>DSS</sub> vs Junction Temperature

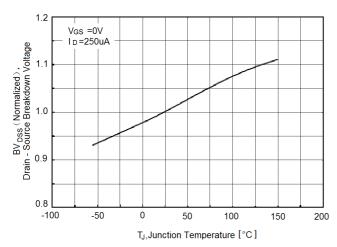


Figure 9. Gate charge waveforms

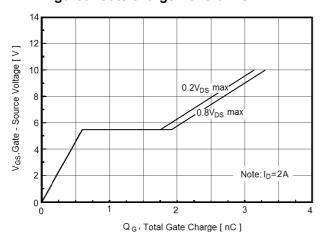


Figure 11. Transient Thermal Impedance

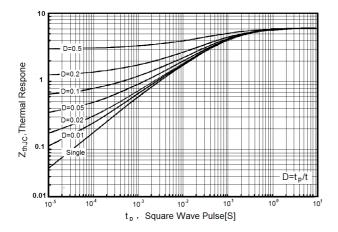


Figure 8. Maximum I<sub>D</sub> vs Junction Temperature

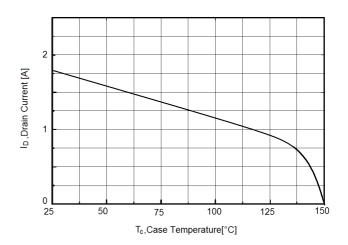
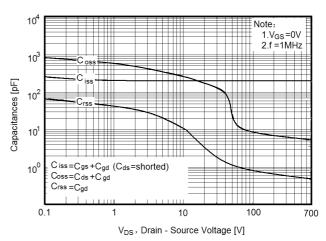
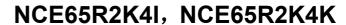


Figure 10. Capacitance

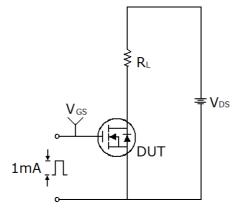


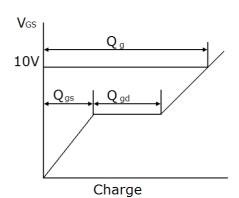




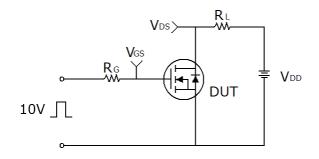
## **Test circuit**

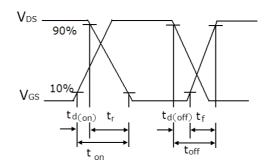
#### 1) Gate charge test circuit & Waveform



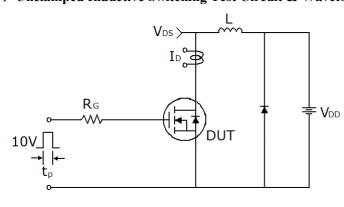


#### 2) Switch Time Test Circuit:

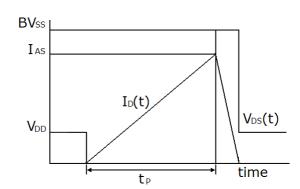




#### 3) Unclamped Inductive Switching Test Circuit & Waveforms

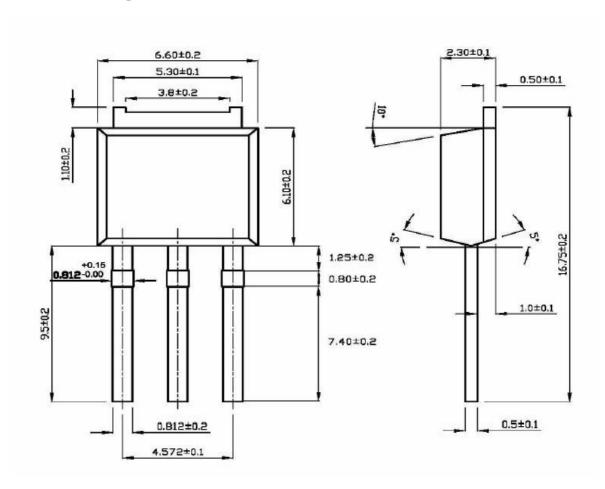


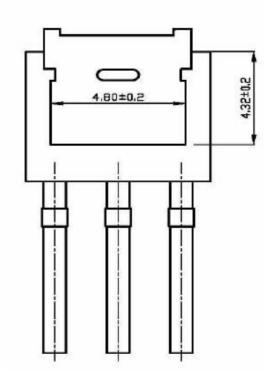
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# **TO-251 Package Information**

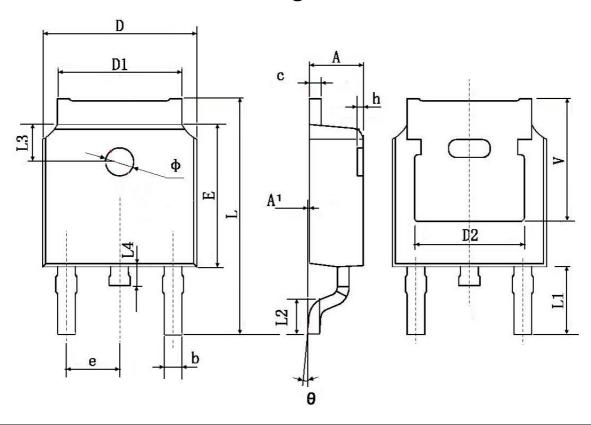




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# **TO-252 Package Information**



Comphal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.83	0 TYP.	0.190	TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.90	2.900 TYP.		TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.60	1.600 TYP.		TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.35	5.350 TYP.		TYP.	

# 新加華 CEPOWER

#### NCE65R2K4I, NCE65R2K4K

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